

ATS-Etcher Series

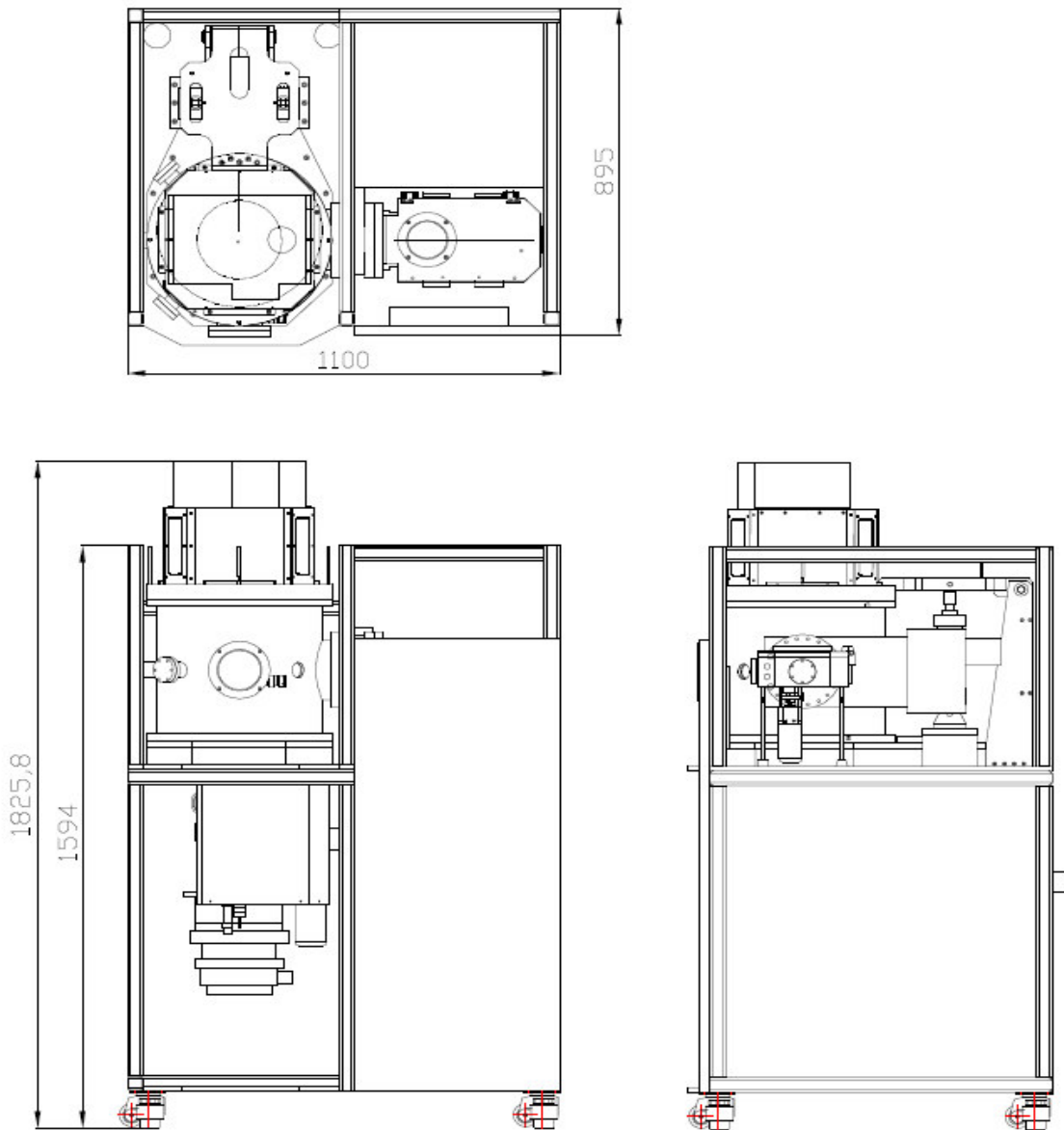
High Density Plasma Etching System for Magnetic Materials



Special Features

- ◆ TCP etching system for R&D and small scale production
- ◆ Automatic robot transporting system
- ◆ Mechanical chuck and He cooling system
- ◆ Applications
Metal, oxide, magnetic materials etching
- ◆ Wafer capacity
1 × 4"
- ◆ Average throughput
Up to 250,000 wafers per year
- ◆ Dimension
1100L × 1830H × 900W (mm³)
- ◆ Others
Power : RF 1kW for TCP source
RF 600W for bias voltage
Gas : C₂F₆ / He / SF₆ / B₆H₆ / Cl₂/ Ar
Substrate material : Si/SiO₂
Pump : rotary(450l/min, 900l/min) & turbo(500l/s)

◇ Layout



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